

Exhibit A

TOWNSEND
and
TOWNSEND
and
CREW

LLP

Denver, Colorado
Tel 303 571-4000

San Francisco

Palo Alto, California
Tel 650 326-2400

Two Embarcadero Center
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Seattle, Washington
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FACSIMILE COVER SHEET

Date: <i>January 2, 2001</i> November 08, 2000	Client & Matter Number : 018865-58	No. Pages (including this one): 2
To: MARIA CRISTINA B. ESTACIO DOUG DOLAN	At Fax Number: 011 63 32 4005 ³ 57 1 207 775-8026	Confirmation Phone Number:
From : Kevin T. LeMond	(4593)	

Message:

PLEASE DELIVER IMMEDIATELY.

RE: DUAL STACKED DIE PACKAGE PATENT APPLICATION

Attached is the drawing for the above identified application. Please review the drawings and let me know if there are any changes.



Original Will:	<input type="checkbox"/>	BE SENT BY MAIL	<input type="checkbox"/>	BE SENT BY FEDEX/OVERNIGHT COURIER	<input type="checkbox"/>	BE SENT BY MESSENGER	<input checked="" type="checkbox"/>	NOT BE SENT
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Faxed:

Return to: Lata Olivier - (4586)

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06156

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 CONNECTION TEL 06156#01163323400561
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TOWNSEND

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Message:

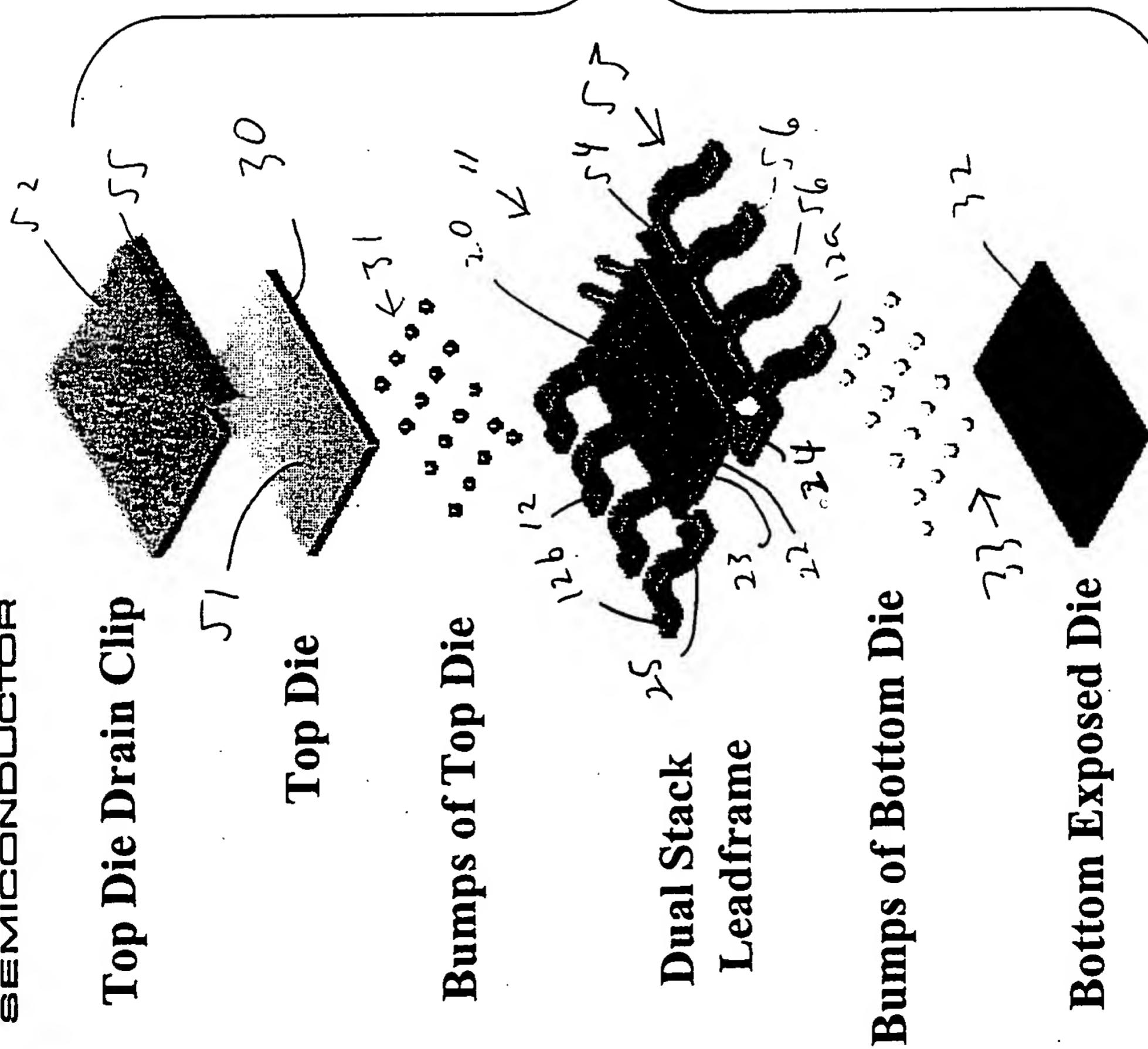
PLEASE DELIVER IMMEDIATELY.

RE: DUAL STACKED DIE PACKAGE PATENT APPLICATION

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FAIRCHILD
SEMICONDUCTOR

Dual Stack Die Internal Package Construction



Molded Package

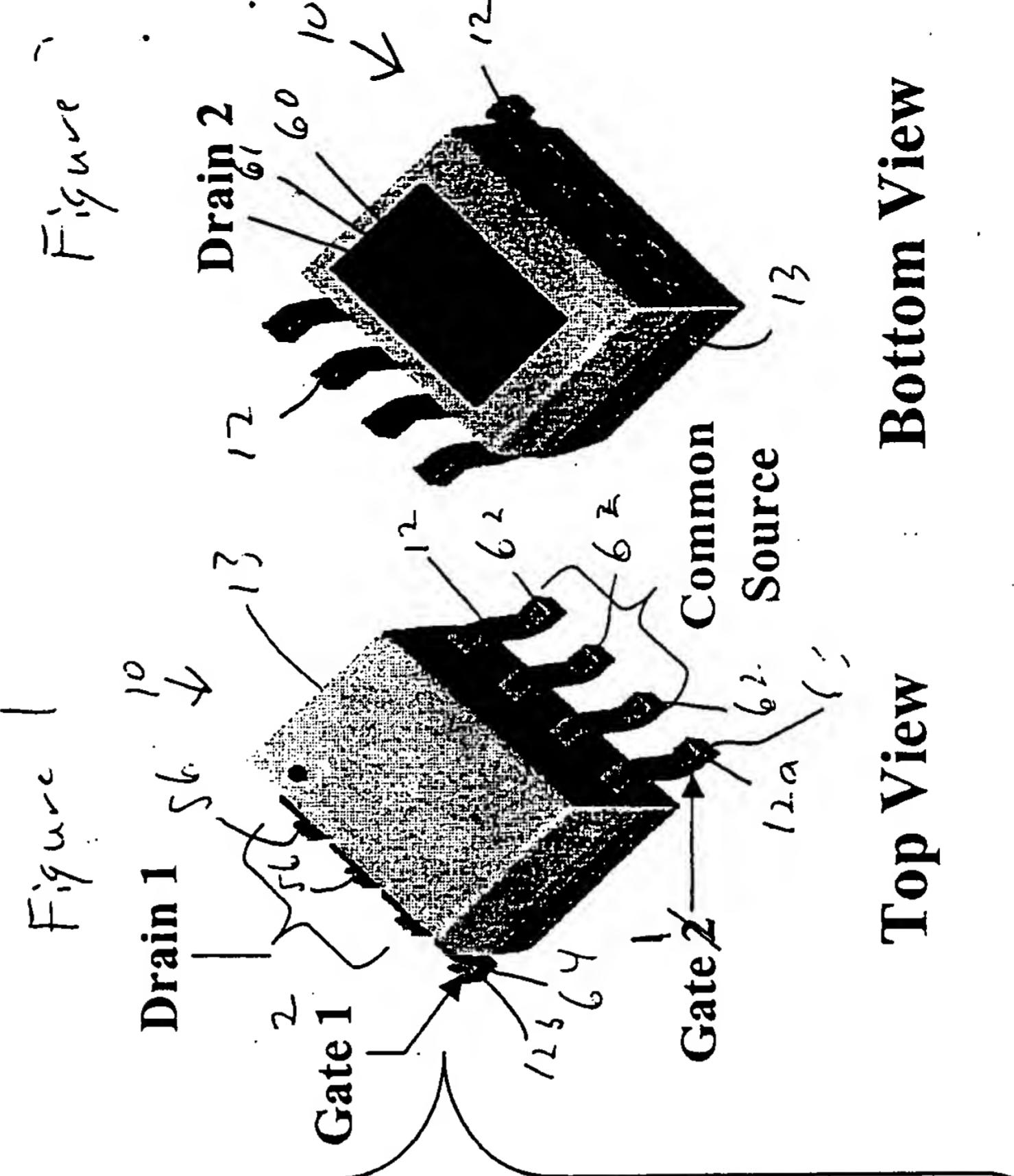


Figure 1

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